

## FEATURED SPEAKERS



**Atsushi Nishikawa**  
Co-Founder and CTO,  
ALLOS Semiconductors



**Dirk Panter**  
State Minister for  
Economic Affairs, Labour,  
Energy and Climate  
Action



**E. Jan Vardaman**  
President and Founder,  
TechSearch International, Inc.



**Gamal Refai-Ahmed**  
Senior Fellow and Chief  
Thermo-Mechanical  
Architect,  
AMD



**Giorgio Cesana**  
Director, Heterogeneous  
Integration Transformation  
Program, Global Technology R&D,  
STMicroelectronics



**Harald Kuhn**  
Executive Director,  
Fraunhofer ENAS



**Jean-Marc Yannou**  
VP Strategy & Innovation,  
Murata



**Nicolai Walter**  
Co-Founder and CEO,  
Pixel Photonics



**Nicole Tien**  
Senior Technical Program  
Manager,  
ASE Europe



**Rajesh Mandamparambil**  
Senior Technical Leader in  
Advanced Semiconductor  
Packaging and Heterogeneous  
Integration,  
NXP Semiconductors



**Shripad Gokhale**  
Senior Principal Engineer-  
Semiconductor Packaging R&D,  
Intel Corporation



**Volker Herbig**  
Vice President,  
BU Microsystems  
& Photonics,  
X-FAB

## KEY FIGURES

**180**

Attendees

**28**

Speakers

**12**

Sponsors

**23**

Exhibitors

**28**

Presentations

**15**

Media Partners



*This summit connects KLA with industry leaders to exchange insights and address manufacturing challenges. Collaboration across the supply chain is critical to advancing next-generation technologies like heterogeneous integration, and participation supports innovation across the evolving advanced packaging ecosystem.*

**Nava Shpaisman, Strategic Collaboration Manager, KLA**



## SPONSORS

Platinum



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## EXHIBITORS



## SPEAKERS



Regular dialogue across the semiconductor ecosystem is essential to transform emerging trends into practical solutions. The SEMI 3D & Systems Summit provides a unique forum to exchange ideas, identify new challenges, and foster partnerships. For Confovis, these interactions have opened valuable new opportunities, strengthening our innovation roadmap and our role in enabling next-generation heterogeneous integration.

Frank Thielert, Head of Business Development, Confovis



SPONSORSHIP & EXHIBITION OPPORTUNITIES



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## KEY ATTENDING COMPANIES

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## PHOTO GALLERY



## VIDEO GALLERY

<p><b>Kurt Herremans</b> imec</p>	<p><b>Mahdi Samadi Khoshkhou</b> Carl Zeiss Microscopy</p>	<p><b>Gamal Refai-Ahmed</b> AMD</p>	<p><b>Robert Hillinger</b> Kistler Instrumente AG</p>
	<p><b>Watch More!</b></p>		
<p><b>Joscha Malin</b> Comet</p>	<p><b>Mohamed Elghazzali</b> Evatec AG</p>	<p><b>Vishal Saroha</b> Yole Group</p>	

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